

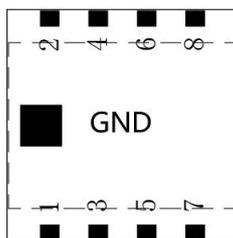
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

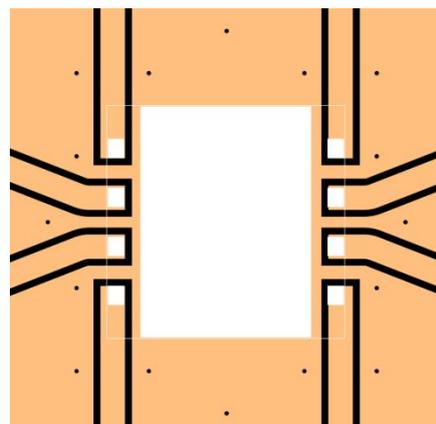
NO.	Specification					
		LPF1	LPF2	LPF3	LPF4	
1	Frequency range (MHz)	30~46	46~72	72~115	115~180	
2	Insertion Loss (dB) @25°C	1.5	1.5	1.5	1.8	
3	Ripple (dB)	1.0	1.0	1.0	1.0	
4	VSWR (In BW)	2.0	2.0	2.0	2.0	
5	Impedance (Ω)	50	50	50	50	
6	Attenuation (dB)	2-d Harm Rej	50	50	50	50
		3-d Harm Rej	50	50	50	50
		2100~2190 MHz	60	60	60	60
Operating & Storage Condition (Component)						
Operation Temperature Range: -40°C ~ +85°C						
Storage Temperature Range: -40°C~ +85°C						
Storage Condition before Soldering (Included packaging material)						
Storage Temperature Range: +5 ~ +40 °C						
Humidity: 30 to 70% relative humidity						

Construction



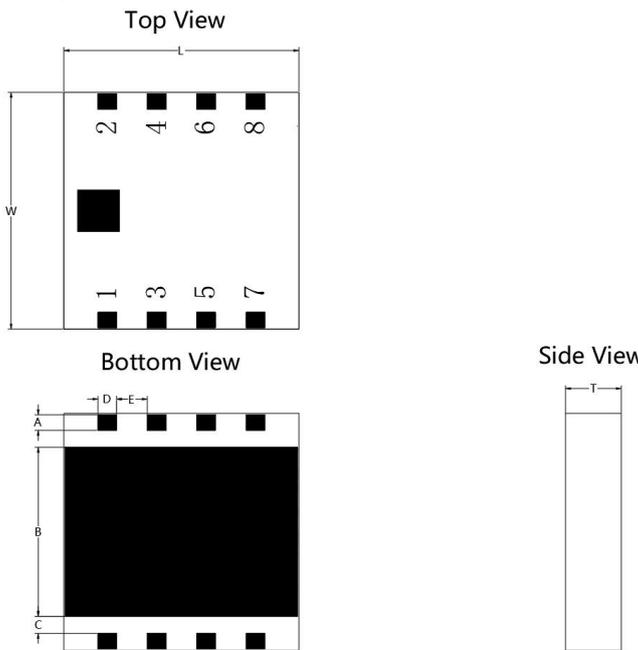
PIN	Connection	PIN	Connection
1	LPF1 input Port	2	LPF1 output Port
3	LPF2 input Port	4	LPF2 output Port
5	LPF3 input Port	6	LPF3 output Port
7	LPF4 input Port	8	LPF4 output Port

Mounting Considerations

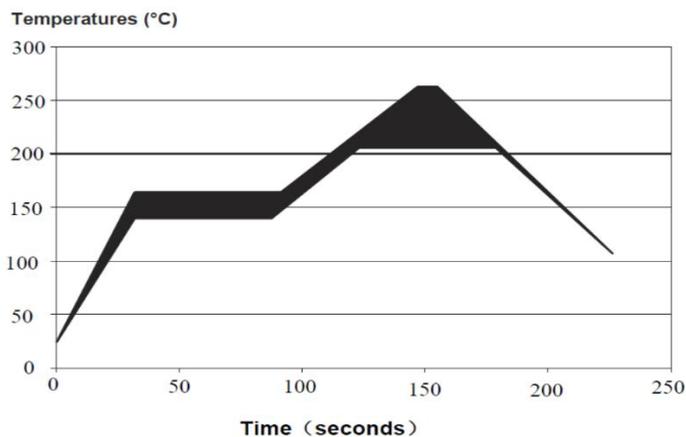


Unit: mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	13.80 ± 0.30
	W	14.00 ± 0.30
	T	2.80 ± 0.20
	A	0.92 ± 0.10
	B	10.00 ± 0.10
	C	1.00 ± 0.10
	D	1.10 ± 0.10
	E	1.80 ± 0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.